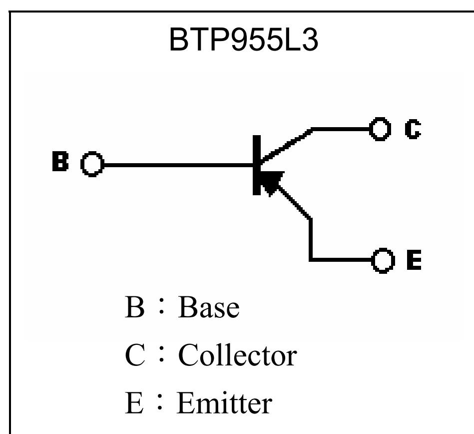
PNP Epitaxial Planar High Current (High Performance) Transistor

BTP955L3

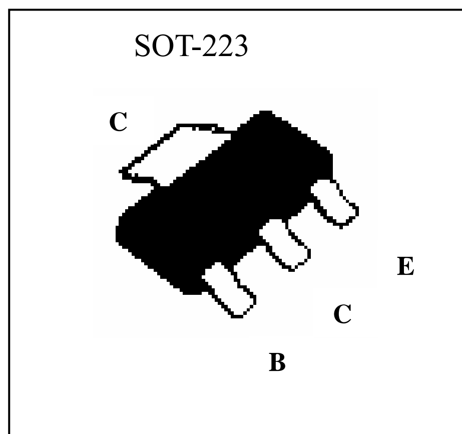
Features

- 4 Amps continuous current, up to 10 Amps peak current
- Very low saturation voltage
- Excellent gain characteristics specified up to 3 Amps
- Ptot=3Watts
- Extremely low equivalent on resistance, $R_{CE(SAT)}$=90mΩ at 3A
- Pb-free lead plating and halogen-free package

Symbol

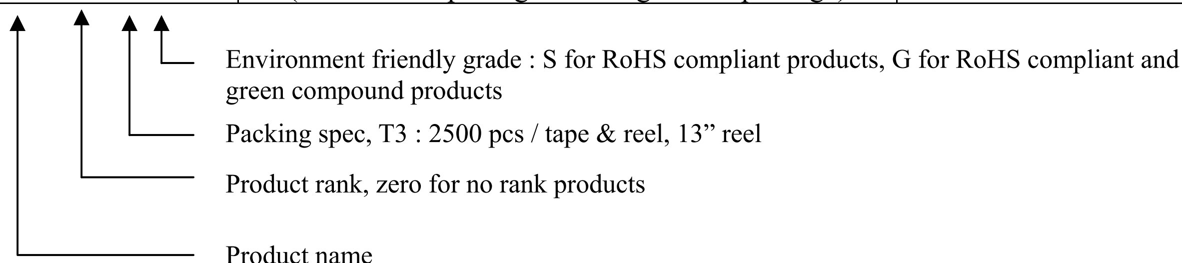


Outline



Ordering Information

Device	Package	Shipping
BTP955L3-X-T3-G	SOT-223 (Pb-free lead plating and halogen-free package)	2500 pcs / tape & reel



Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Limits	Unit
Collector-Base Voltage	V_{CBO}	-180	V
Collector-Emitter Voltage	V_{CEO}	-140	V
Emitter-Base Voltage	V_{EBO}	-6	V
Continuous Collector Current	I_C	-4	A
Peak Collector Current	I_{CP}	-10	A
Base Current	I_B	-1	A
Power Dissipation @T_A=25°C	Pd	3 (Note 1)	W
ESD susceptibility		4000 (Note 2)	V
Operating and Storage Temperature Range	Tj ; Tstg	-55 ~ +150	°C

Thermal Data

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-case, max	$R_{\theta JC}$	12.5	°C/W
Thermal Resistance, Junction-to-ambient, max	$R_{\theta JA}$	41 (Note 1)	°C/W

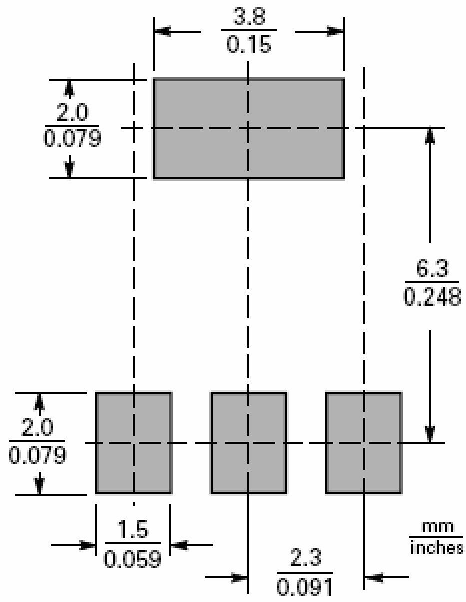
Note: 1.The power which can be dissipated assuming the device is mounted in a typical manner on a P.C.B. with copper equal to 4 square inch minimum.
2.Human body model, 1.5kΩ in series with 100pF

Characteristics (Ta=25°C, unless otherwise specified)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BV_{CBO}	-180	-210	-	V	I_C=-100μA
BV_{CER}	-180	-210	-	V	I_C=-1μA, R_{BE}≤1kΩ
*BV_{CEO}	-140	-170	-	V	I_C=-10mA
BV_{EBO}	-6	-8	-	V	I_E=-100μA
I_{CBO}	-	-	-50	nA	V_{CB}=-150V
I_{CER}	-	-	-50	nA	V_{CE}=-150V, R_{BE}≤1kΩ
I_{EBO}	-	-	-10	nA	V_{EB}=-6V
*$V_{CE(sat)}1$	-	-40	-60	mV	I_C=-100mA, I_B=-5mA
*$V_{CE(sat)}2$	-	-70	-120	mV	I_C=-500mA, I_B=-50mA
*$V_{CE(sat)}3$	-	-110	-150	mV	I_C=-1A, I_B=-100mA
*$V_{CE(sat)}4$	-	-270	-370	mV	I_C=-3A, I_B=-300mA
*$V_{BE(sat)}$	-	-930	-1110	mV	I_C=-3A, I_B=-300mA
*$V_{BE(on)}$	-	-830	-950	mV	V_{CE}=-5V, I_C=-3A
$h_{FE}1$	100	200	-	-	V_{CE}=-5V, I_C=-10mA
$h_{FE}2$	100	200	300	-	V_{CE}=-5V, I_C=-1A
*$h_{FE}3$	75	140	-	-	V_{CE}=-5V, I_C=-3A
*$h_{FE}4$	-	10	-	-	V_{CE}=-5V, I_C=-10A
f_T	-	110	-	MHz	V_{CE}=-10V, I_C=-100mA, f=50MHz
Cob	-	40	-	pF	V_{CB}=-20V, f=1MHz
ton		68		ns	I_C=-1A, I_B1=-100mA, I_B2=100mA, V_{CC}=-50V
toff		1030		ns	

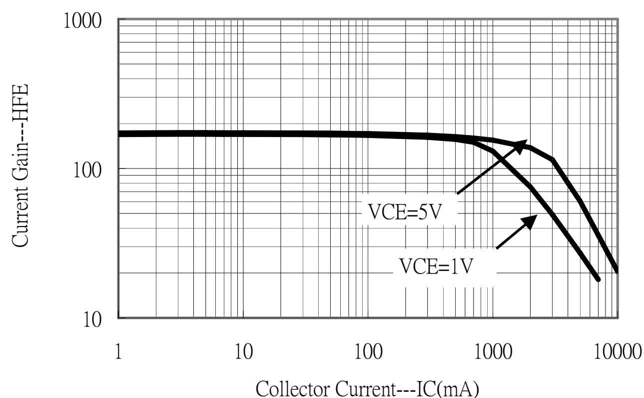
*Pulse Test: Pulse Width ≤380μs, Duty Cycle≤2%

Recommended soldering footprint

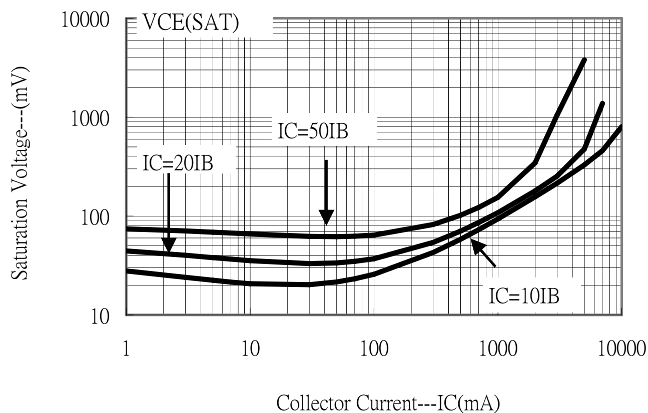


Typical Characteristics

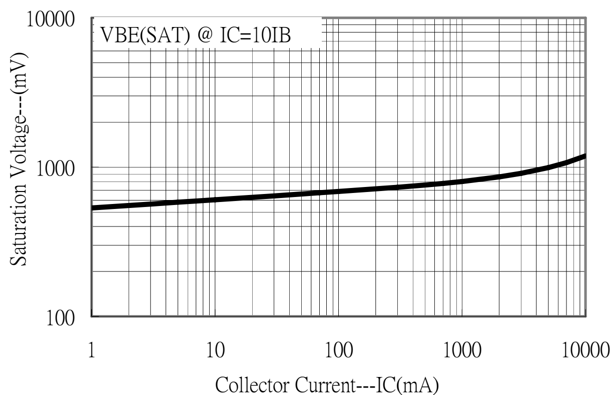
Current Gain vs Collector Current



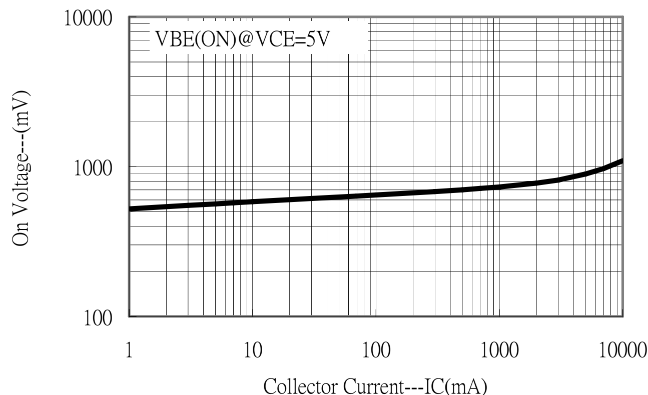
Saturation Voltage vs Collector Current



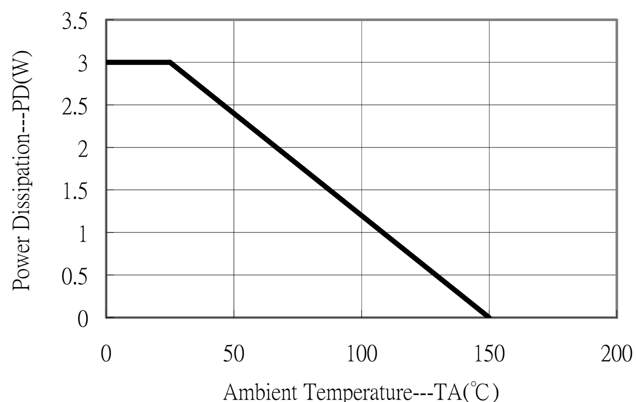
Saturation Voltage vs Collector Current



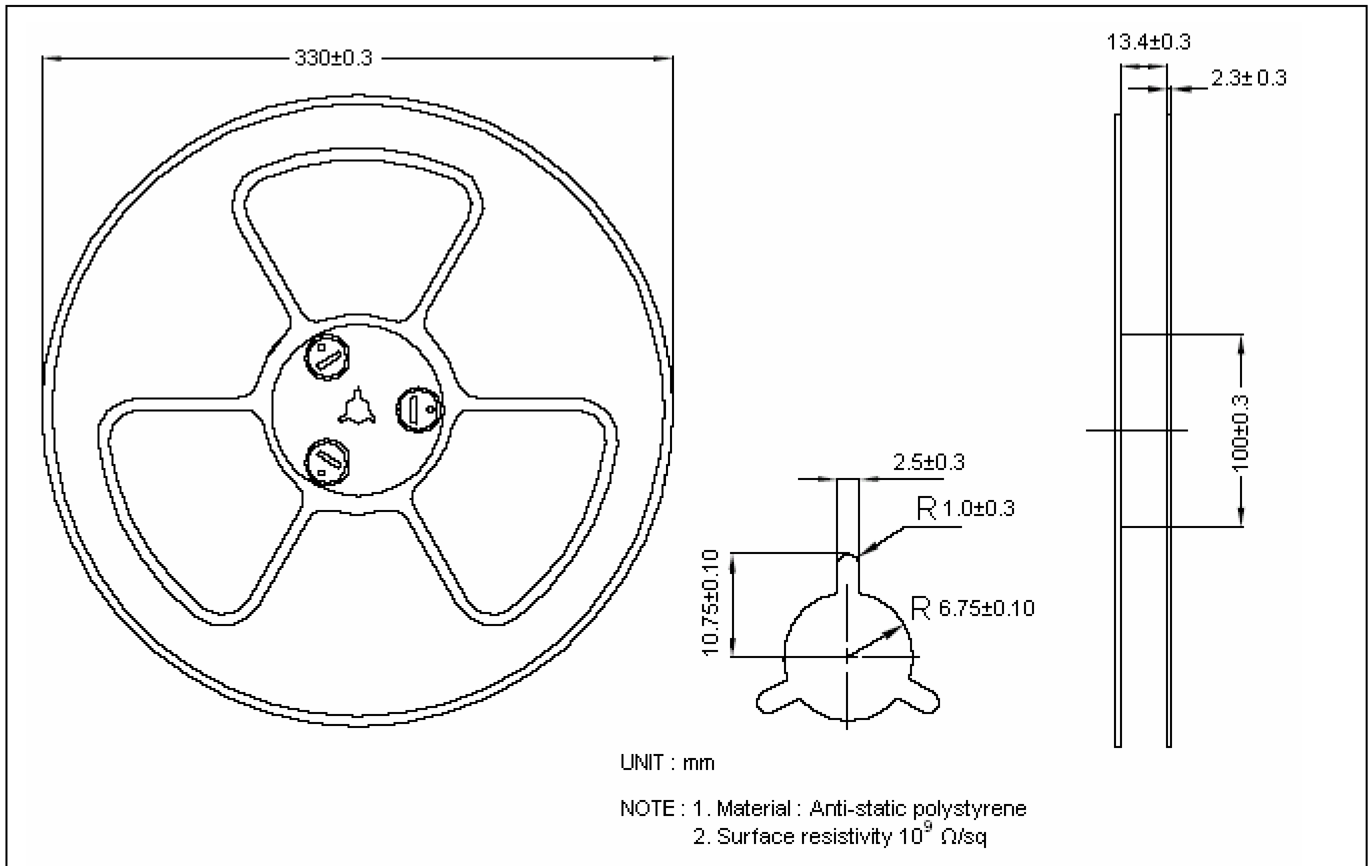
On Vottage vs Collector Current



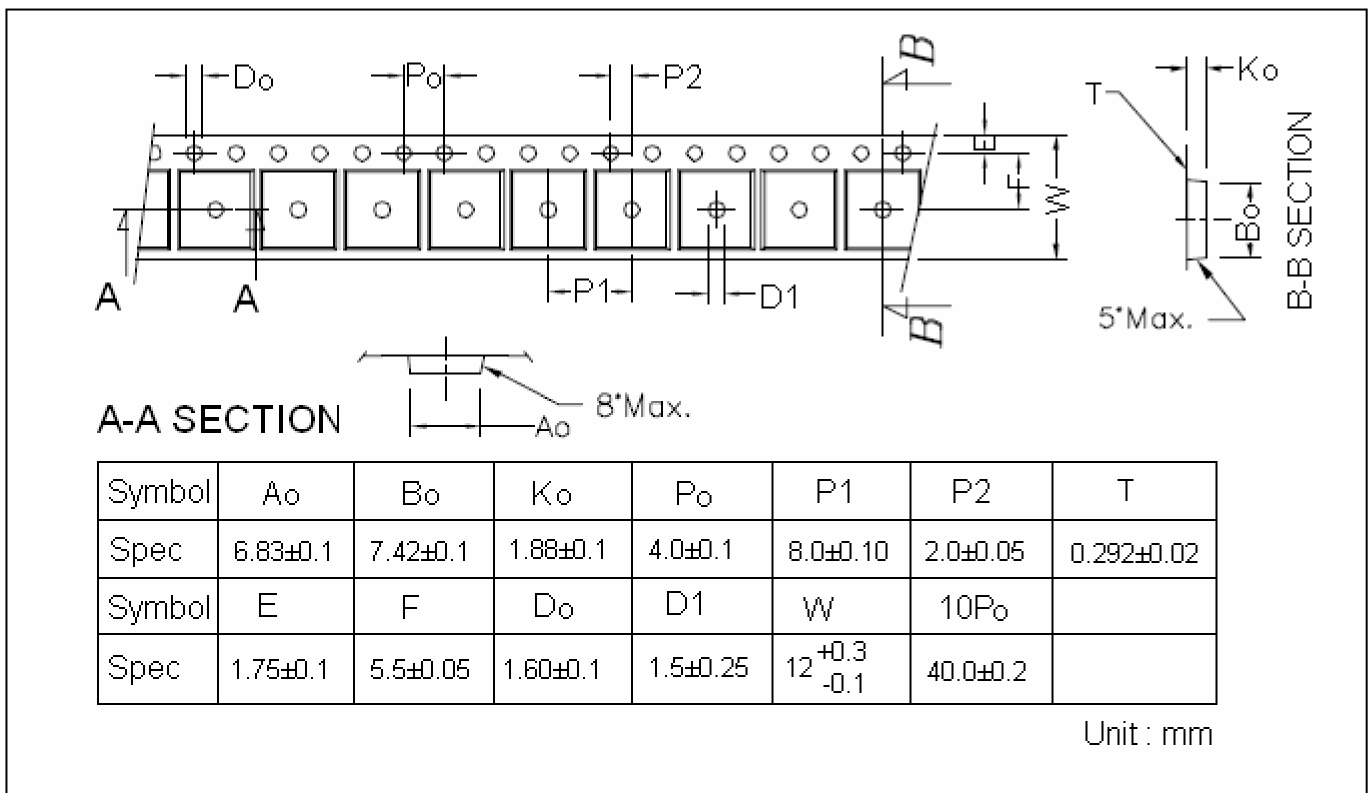
Power Derating Curve



Reel Dimension



Carrier Tape Dimension

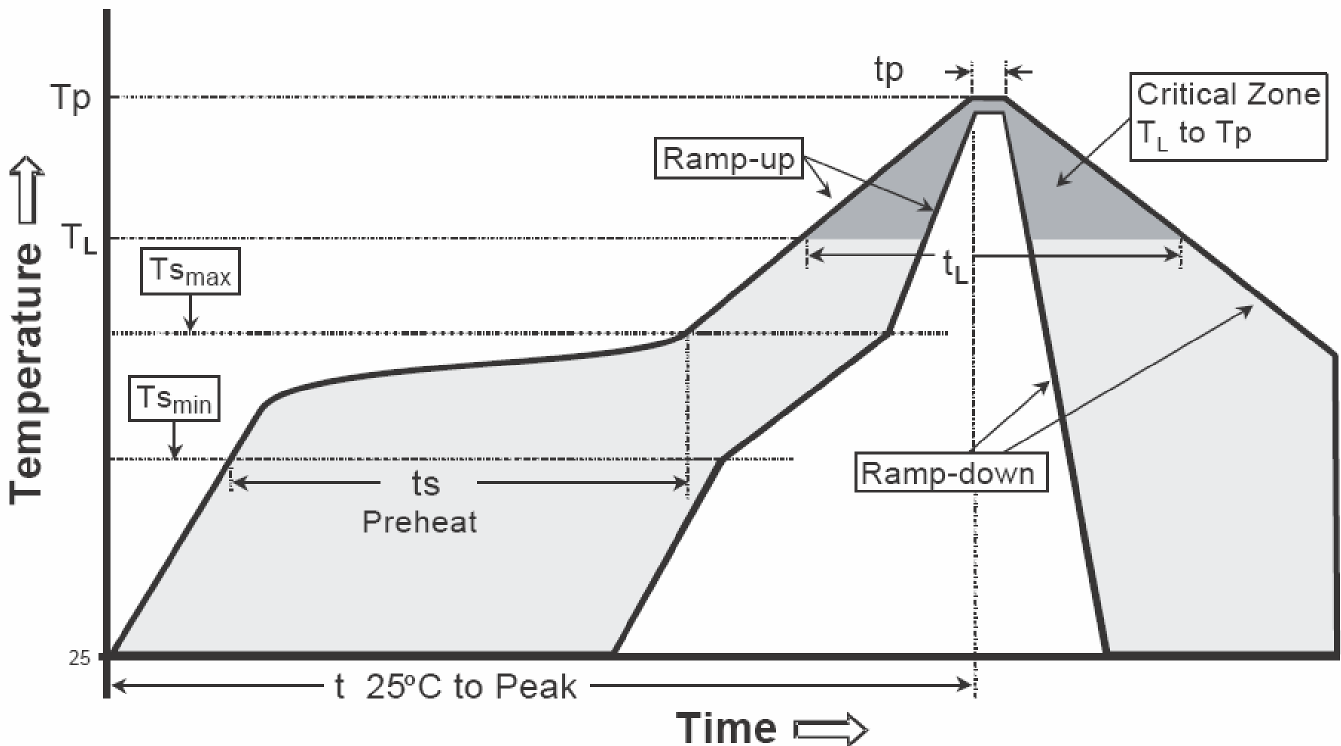


Symbol	Ao	Bo	Ko	Po	P1	P2	T
Spec	6.83±0.1	7.42±0.1	1.88±0.1	4.0±0.1	8.0±0.10	2.0±0.05	0.292±0.02
Symbol	E	F	Do	D1	W	10Po	
Spec	1.75±0.1	5.5±0.05	1.60±0.1	1.5±0.25	12 +0.3 -0.1	40.0±0.2	

Recommended wave soldering condition

Product	Peak Temperature	Soldering Time
Pb-free devices	260 +0/-5 °C	5 +1/-1 seconds

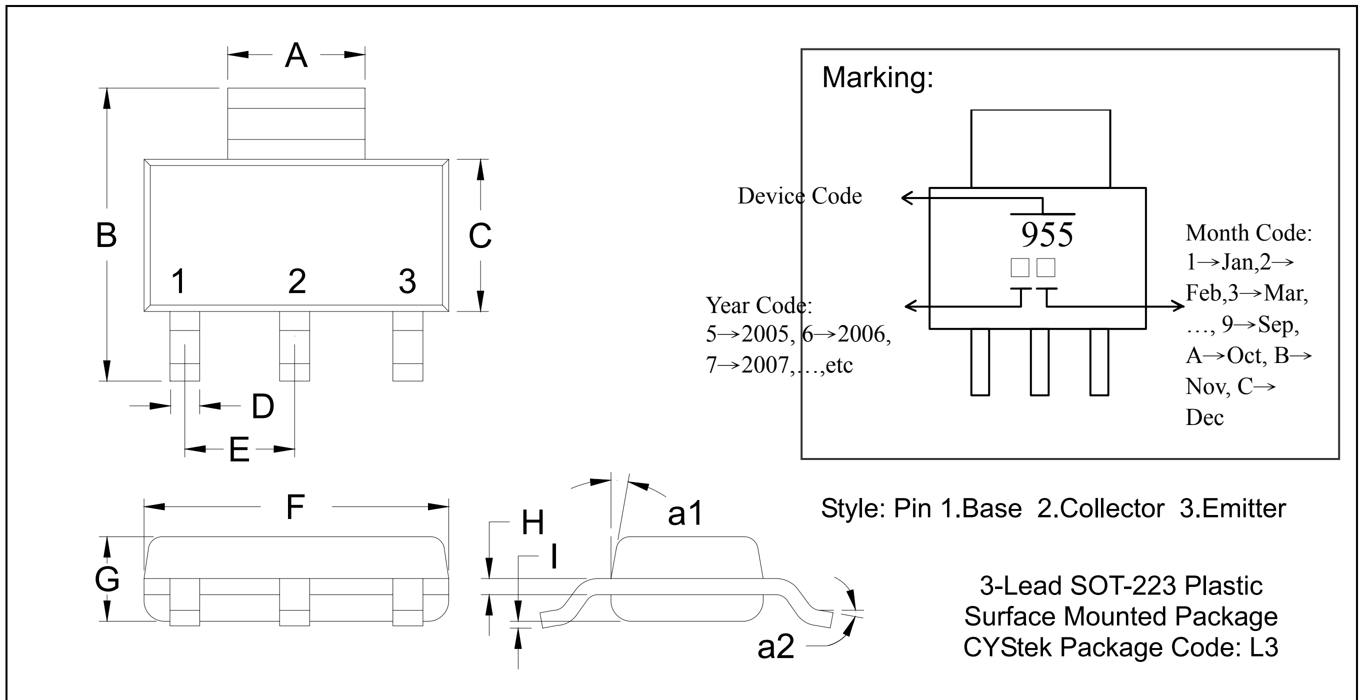
Recommended temperature profile for IR reflow



Profile feature	Sn-Pb eutectic Assembly	Pb-free Assembly
Average ramp-up rate (Tsmax to Tp)	3°C/second max.	3°C/second max.
Preheat −Temperature Min(Ts min) −Temperature Max(Ts max) −Time(ts min to ts max)	100°C 150°C 60-120 seconds	150°C 200°C 60-180 seconds
Time maintained above: −Temperature (TL) − Time (tL)	183°C 60-150 seconds	217°C 60-150 seconds
Peak Temperature(TP)	240 +0/-5 °C	260 +0/-5 °C
Time within 5°C of actual peak temperature(tp)	10-30 seconds	20-40 seconds
Ramp down rate	6°C/second max.	6°C/second max.
Time 25 °C to peak temperature	6 minutes max.	8 minutes max.

Note : All temperatures refer to topside of the package, measured on the package body surface.

SOT-223 Dimension



*: Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.1142	0.1220	2.90	3.10	G	0.0551	0.0709	1.40	1.80
B	0.2638	0.2874	6.70	7.30	H	0.0098	0.0138	0.25	0.35
C	0.1299	0.1457	3.30	3.70	I	0.0008	0.0039	0.02	0.10
D	0.0236	0.0315	0.60	0.80	a1	*13°	-	*13°	-
E	*0.0906	-	*2.30	-	a2	0°	10°	0°	10°
F	0.2480	0.2638	6.30	6.70					

Notes: 1.Controlling dimension: millimeters.
2.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
3.If there is any question with packing specification or packing method, please contact your local CYStek sales office.

Material:

- Lead: Pure tin plated.
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0.

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